



# PMEG2010EPAS

20 V, 1 A low VF MEGA Schottky barrier rectifier

19 January 2015

Product data sheet

## 1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in an ultra thin DFN2020D-3 (SOT1061D) leadless small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

## 2. Features and benefits

- Average forward current  $I_{F(AV)} \leq 1$  A
- Reverse voltage  $V_R \leq 20$  V
- Low forward voltage  $V_F \leq 375$  mV
- Low reverse current
- Reduced Printed-Circuit-Board (PCB) area requirements
- Exposed heat sink (cathode pad) for excellent thermal and electrical conductivity
- Leadless small SMD plastic package with visible and solderable side pads
- Suitable for Automatic Optical Inspection (AOI) of solder joints
- AEC-Q101 qualified

## 3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Free-wheeling application
- Reverse polarity protection
- Low power consumption application
- Battery chargers for mobile equipment
- LED backlight for mobile application

## 4. Quick reference data

Table 1. Quick reference data

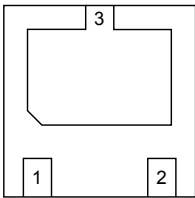

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; $f = 20$ kHz; $T_{amb} \leq 125$ °C; square wave	[1]	-	-	1	A
		$\delta = 0.5$ ; $f = 20$ kHz; $T_{sp} \leq 145$ °C; square wave		-	-	1	A
$V_R$	reverse voltage	$T_j = 25$ °C		-	-	20	V

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 1\text{ A}$ ; $t_p \leq 300\ \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_j = 25\text{ }^\circ\text{C}$ ; pulsed	-	320	375	mV
$I_R$	reverse current	$V_R = 20\text{ V}$ ; $t_p \leq 300\ \mu\text{s}$ ; $\delta \leq 0.02$ ; $T_j = 25\text{ }^\circ\text{C}$ ; pulsed	-	335	1900	$\mu\text{A}$

[1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $\text{Al}_2\text{O}_3$ , standard footprint.

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A	anode	 <p>Transparent top view <b>DFN2020D-3 (SOT1061D)</b></p>	 <p>006aab624</p>
2	A	anode		
3	K	cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG2010EPAS	DFN2020D-3	DFN2020D-3: plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body 2 x 2 x 0.65 mm	SOT1061D

## 7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG2010EPAS	CR

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage	$T_j = 25\text{ °C}$		-	20	V
$I_F$	forward current	$T_{sp} \leq 140\text{ °C}; \delta = 1$		-	1.4	A
$I_{F(AV)}$	average forward current	$\delta = 0.5; f = 20\text{ kHz}; T_{amb} \leq 125\text{ °C};$ square wave	[1]	-	1	A
		$\delta = 0.5; f = 20\text{ kHz}; T_{sp} \leq 145\text{ °C};$ square wave		-	1	A
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1\text{ ms}; \delta \leq 0.25$	[2]	-	7	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 8\text{ ms}; T_{j(init)} = 25\text{ °C};$ square wave	[2]	-	17	A
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[3]	-	500	mW
			[4]	-	960	mW
			[1]	-	1800	mW
$T_j$	junction temperature			-	150	°C
$T_{amb}$	ambient temperature			-55	150	°C
$T_{stg}$	storage temperature			-65	150	°C

[1] Device mounted on a ceramic Printed-Circuit Board (PCB),  $Al_2O_3$ , standard footprint.

[2] Both anode pins connected.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

## 9. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	250	K/W
			[1][3]	-	-	130	K/W
			[1][4]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	12	K/W

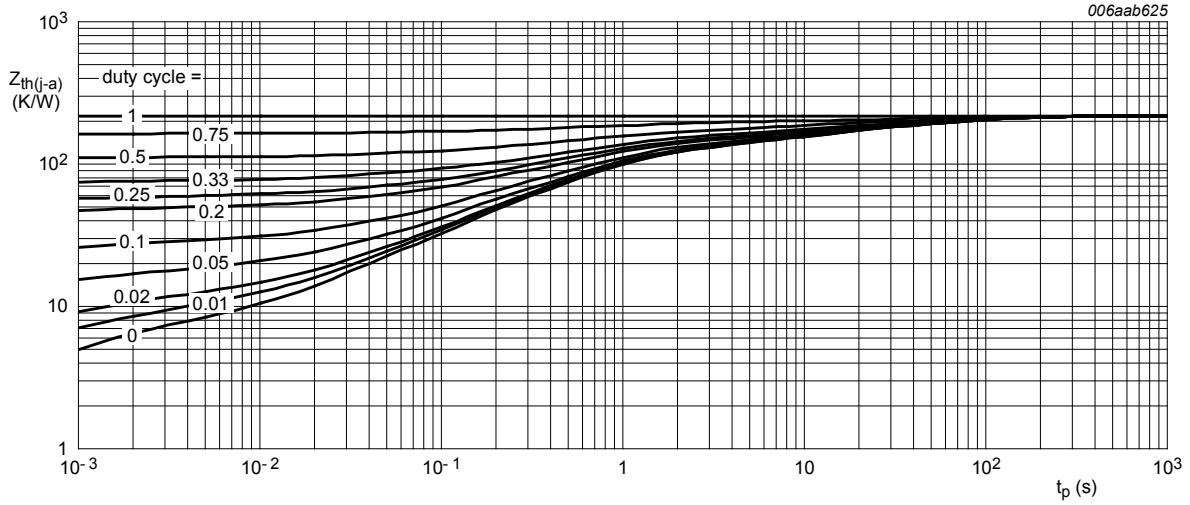
[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses  $P_R$  are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode  $1\text{ cm}^2$ .

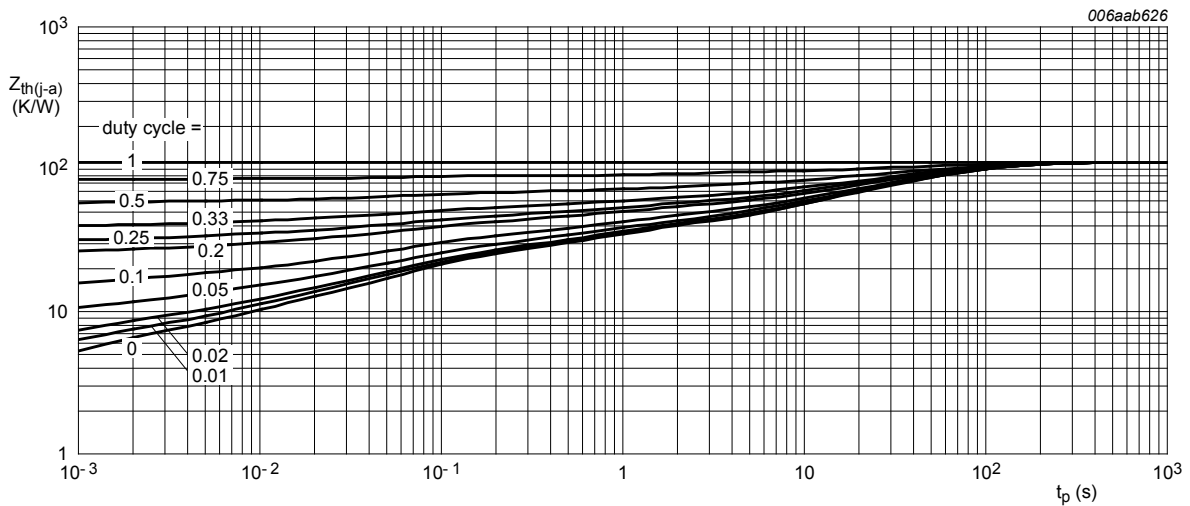
[4] Device mounted on a ceramic PCB,  $Al_2O_3$ , standard footprint.

[5] Soldering point of cathode tab.



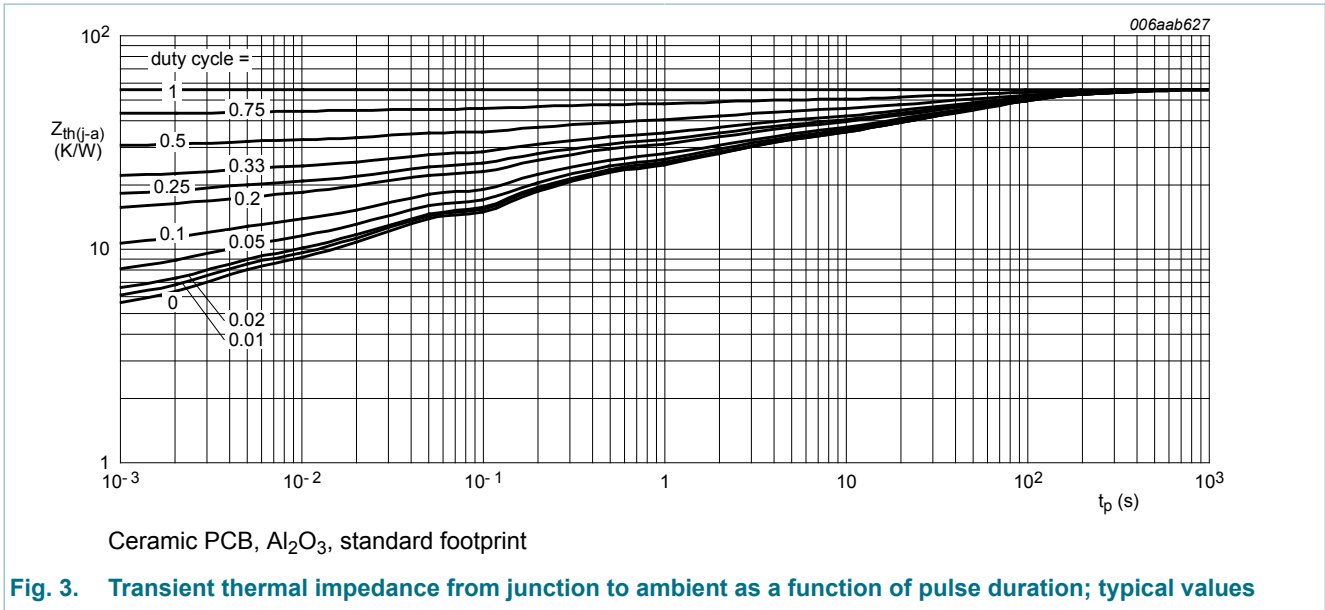
FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

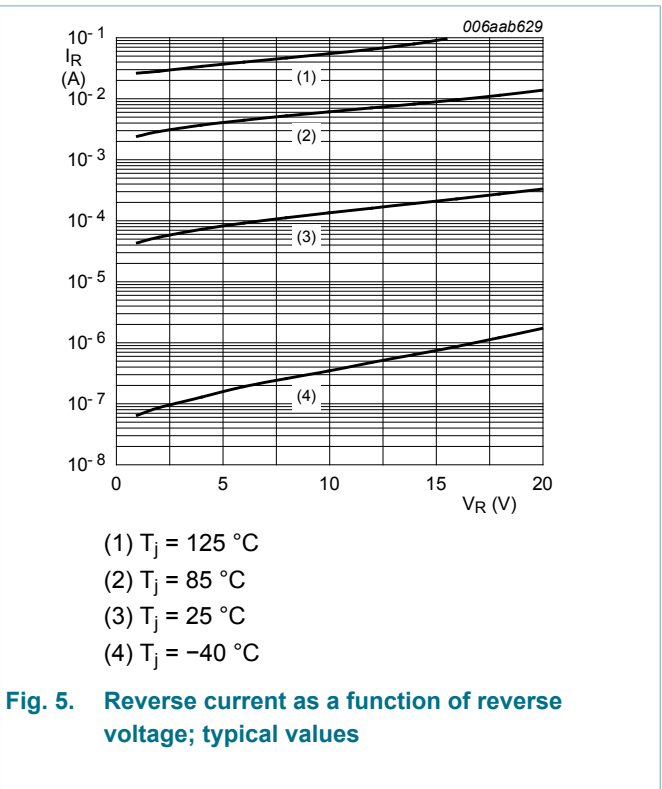
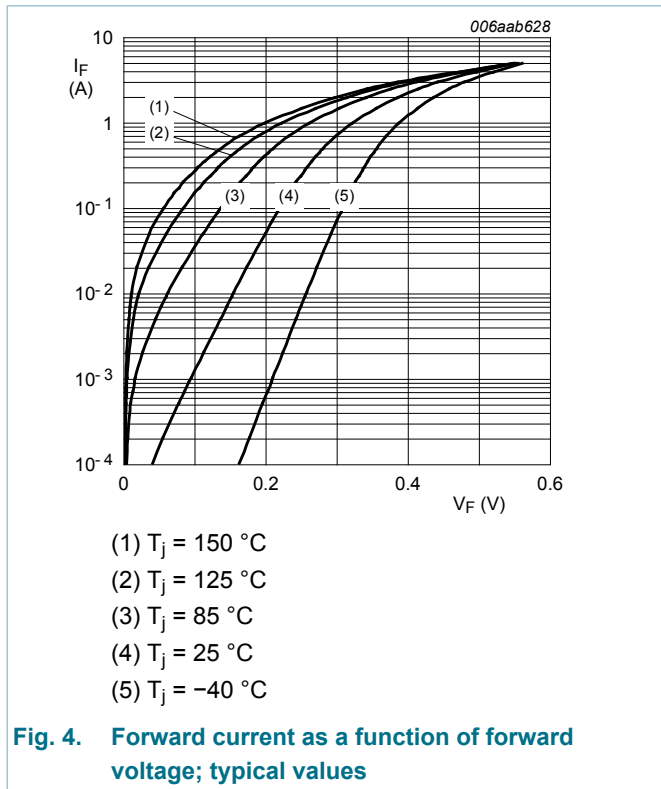
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

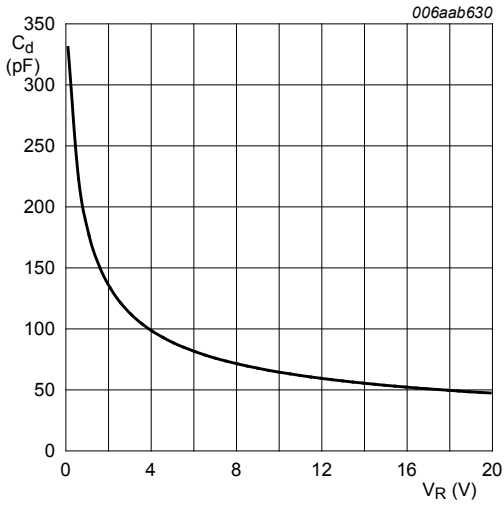


### 10. Characteristics

Table 7. Characteristics

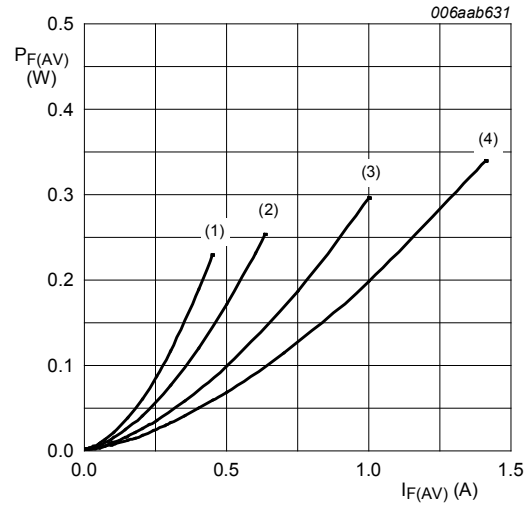
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 10 \text{ mA}$ ; $t_p = 300 \text{ }\mu\text{s}$ ; $\delta = 0.02$ ; $T_J = 25 \text{ }^\circ\text{C}$ ; pulsed	20	-	-	V
$V_F$	forward voltage	$I_F = 0.5 \text{ A}$ ; $t_p \leq 300 \text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_J = 25 \text{ }^\circ\text{C}$ ; pulsed	-	280	-	mV
		$I_F = 1 \text{ A}$ ; $t_p \leq 300 \text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_J = 25 \text{ }^\circ\text{C}$ ; pulsed	-	320	375	mV
$I_R$	reverse current	$V_R = 10 \text{ V}$ ; $t_p \leq 300 \text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_J = 25 \text{ }^\circ\text{C}$ ; pulsed	-	135	-	$\mu\text{A}$
		$V_R = 20 \text{ V}$ ; $t_p \leq 300 \text{ }\mu\text{s}$ ; $\delta \leq 0.02$ ; $T_J = 25 \text{ }^\circ\text{C}$ ; pulsed	-	335	1900	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1 \text{ V}$ ; $f = 1 \text{ MHz}$ ; $T_J = 25 \text{ }^\circ\text{C}$	-	175	-	pF
		$V_R = 10 \text{ V}$ ; $f = 1 \text{ MHz}$ ; $T_J = 25 \text{ }^\circ\text{C}$	-	65	-	pF
$t_{rr}$	reverse recovery time	$I_F = 10 \text{ mA}$ ; $I_R = 10 \text{ mA}$ ; $R_L = 100 \text{ }\Omega$ ; $I_{R(\text{meas})} = 1 \text{ mA}$ ; $T_J = 25 \text{ }^\circ\text{C}$	-	50	-	ns





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^\circ\text{C}$

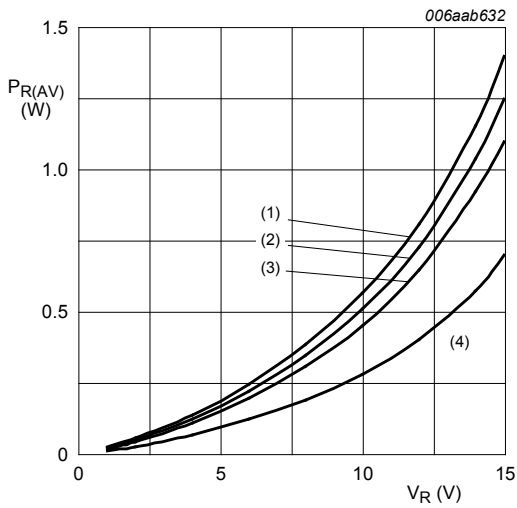
**Fig. 6. Diode capacitance as a function of reverse voltage; typical values**



$T_j = 150 \text{ }^\circ\text{C}$

- (1)  $\delta = 0.1$
- (2)  $\delta = 0.2$
- (3)  $\delta = 0.5$
- (4)  $\delta = 1$

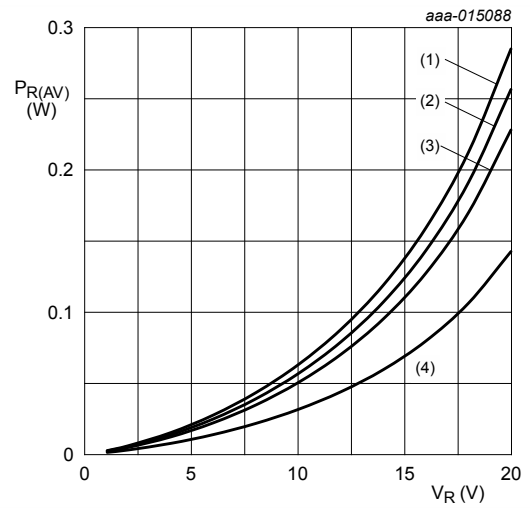
**Fig. 7. Average forward power dissipation as a function of average forward current; typical values**



$T_j = 125 \text{ }^\circ\text{C}$

- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

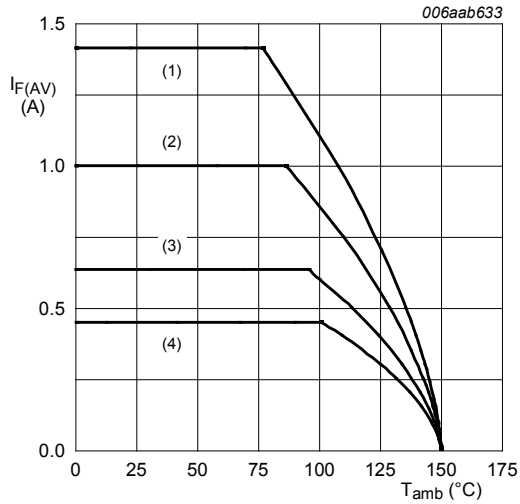
**Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values**



$T_j = 85 \text{ }^\circ\text{C}$

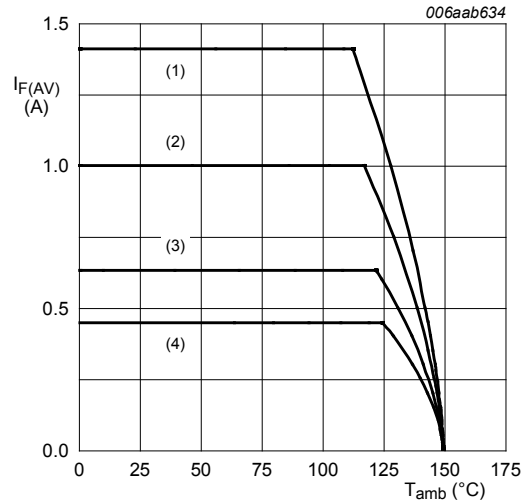
- (1)  $\delta = 1$
- (2)  $\delta = 0.9$
- (3)  $\delta = 0.8$
- (4)  $\delta = 0.5$

**Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values**



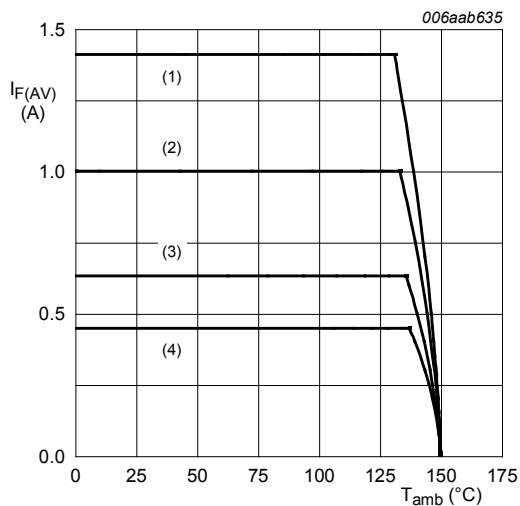
FR4 PCB, standard footprint  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 10. Average forward current as a function of ambient temperature; typical values**



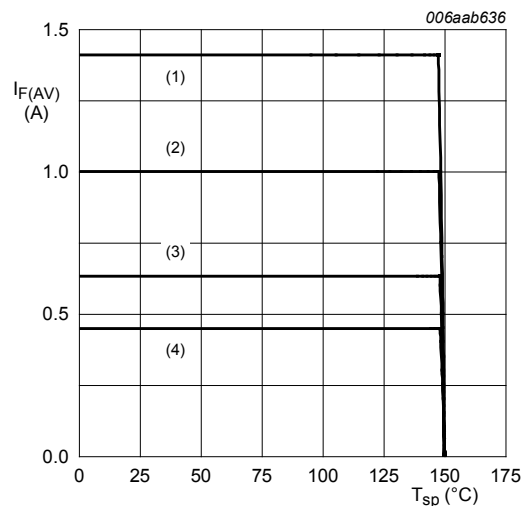
FR4 PCB, mounting pad for cathode  $1\text{ cm}^2$   
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 11. Average forward current as a function of ambient temperature; typical values**



Ceramic PCB,  $\text{Al}_2\text{O}_3$ , standard footprint  
 $T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 12. Average forward current as a function of ambient temperature; typical values**



$T_j = 150\text{ °C}$   
 (1)  $\delta = 1$ ; DC  
 (2)  $\delta = 0.5$ ;  $f = 20\text{ kHz}$   
 (3)  $\delta = 0.2$ ;  $f = 20\text{ kHz}$   
 (4)  $\delta = 0.1$ ;  $f = 20\text{ kHz}$

**Fig. 13. Average forward current as a function of solder point temperature; typical values**



### 11. Test information

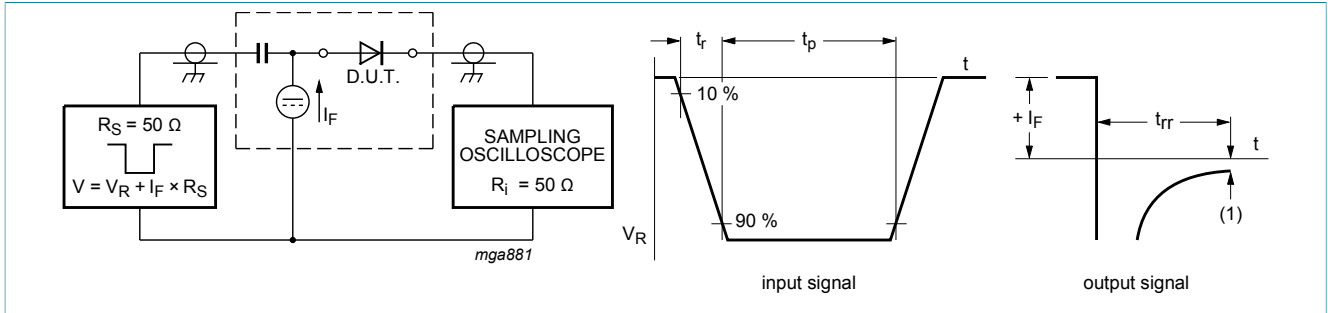


Fig. 14. Reverse recovery time: test circuit and waveforms

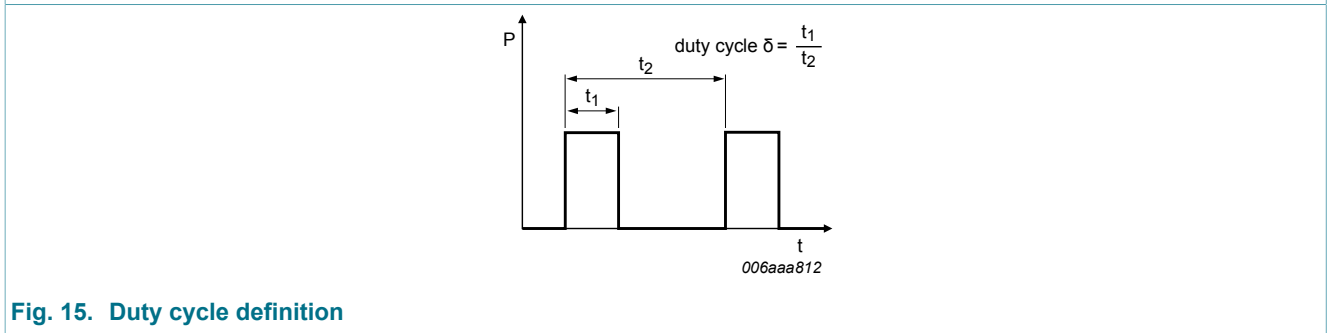


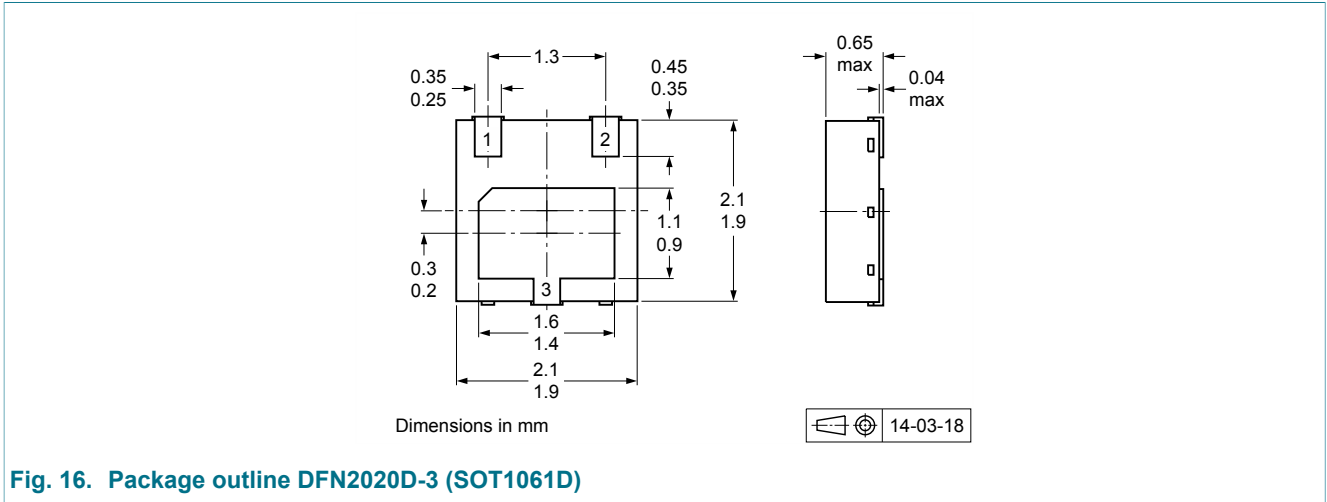
Fig. 15. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:  $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current,  $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current.

#### 11.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

## 12. Package outline



**Fig. 16. Package outline DFN2020D-3 (SOT1061D)**

### 13. Soldering

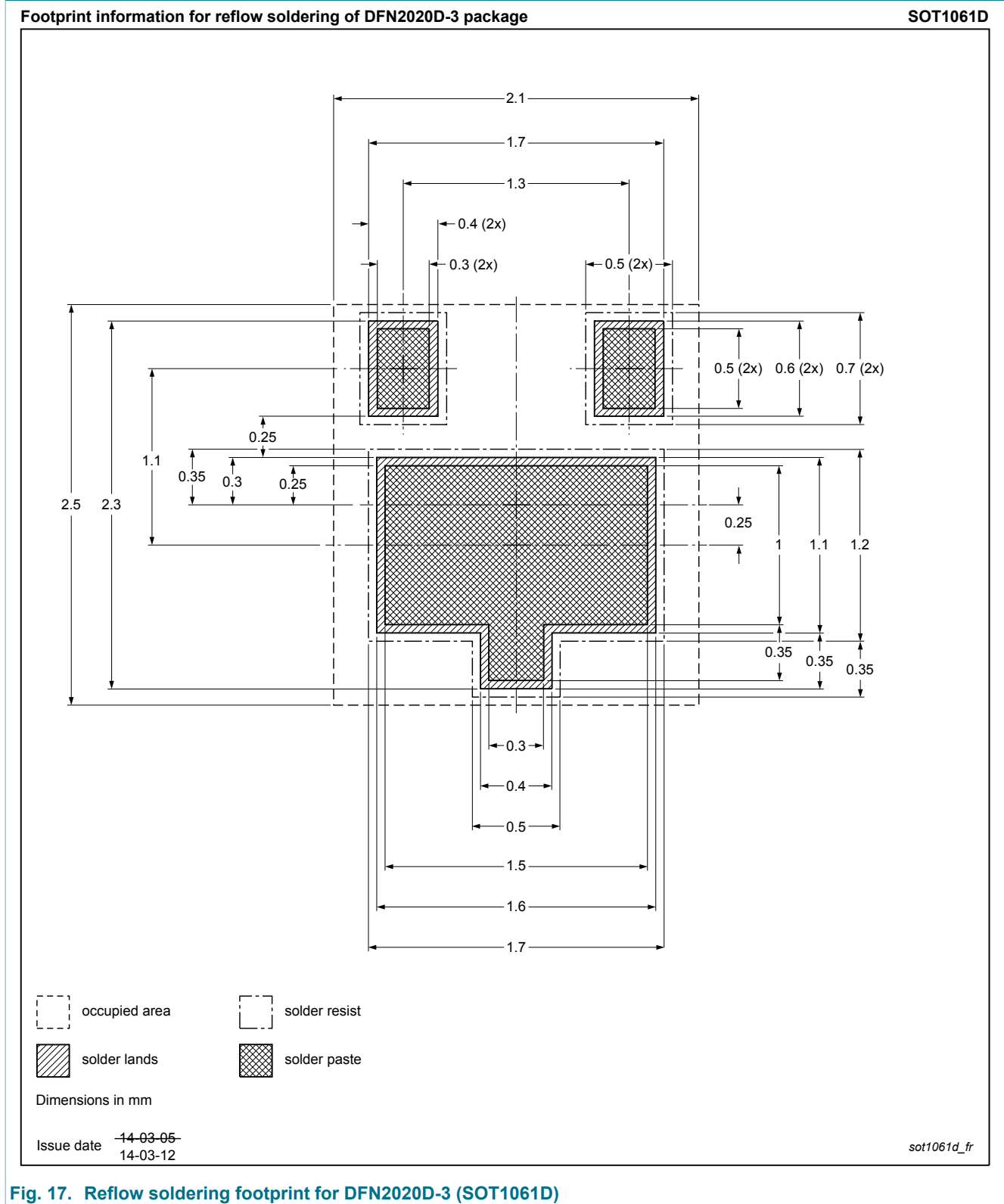


Fig. 17. Reflow soldering footprint for DFN2020D-3 (SOT1061D)

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2010EPAS v.2	20150119	Product data sheet	-	PMEG2010EPAS v.1
Modification:	<ul style="list-style-type: none"><li>Product status changed</li></ul>			
PMEG2010EPAS v.1	20141208	Preliminary data sheet	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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